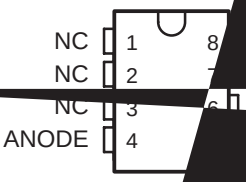
# LM285-2.5, LM385-2.
# MICROPOWER VOLTAGE



**LM285-2.5 . . . D PAC**
**LM385-2.5, LM385B-2.5 . . . D C**
**(TOP VIEW)**

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**LM285-2.5, LM385-2.5, LM3**
**(TOP V**

NC

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Package drawings,
www.ti.com/sc/package

Please be aware that an importa ning av
Texas Instruments semiconductor prod aimers t

PRO DATA information is current as of publication date.
Prod form to specifications per the terms of Texas Instruments
standard warranty. Production processing does not necessarily include
parameters.

**1002.5**

## TYPICAL CHARACTERISTICS†

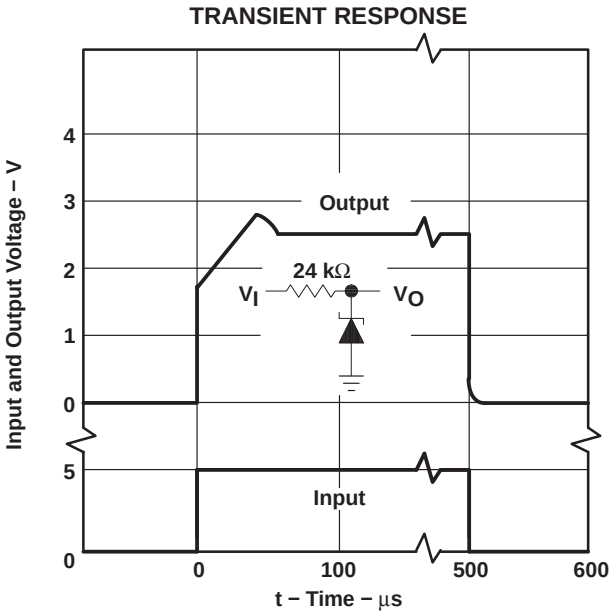



**Figure 9**

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

# LM285-2.5, LM385-2.5, LM385B-2.5
# MICROPOWER VOLTAGE REFERENCES

SLVS023J − JANUARY 1989 − REVISED MARCH 2005

[redacted]

# PACKAGE OPTION ADDENDUM

www.ti.com

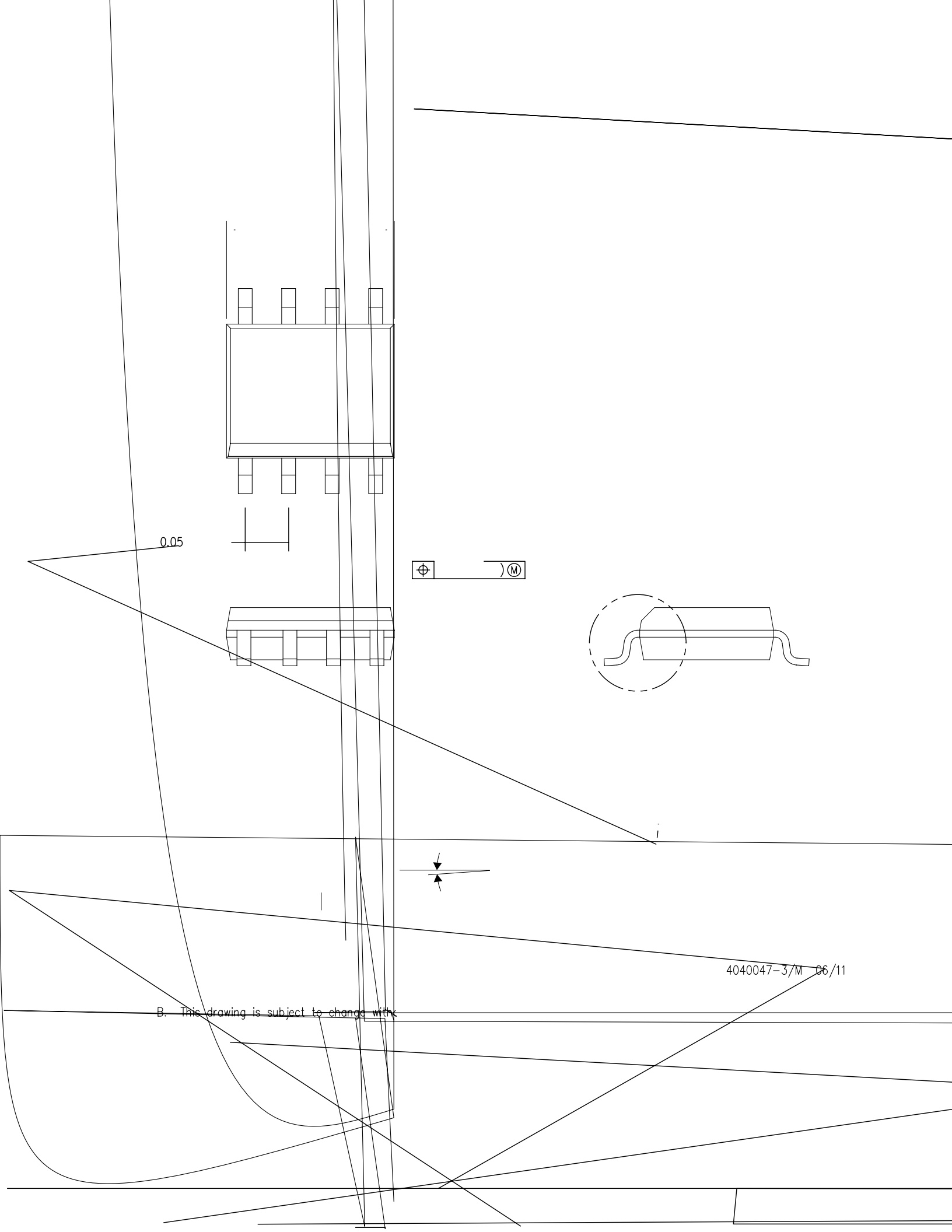
24-Jan-2013

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| LM285D-2-5 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 285-25 | Samples |
| LM285DE4-2-5 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 285-25 | Samples |
| LM285DG4-2-5 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 285-25 | Samples |
| LM285DR-2-5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 285-25 | Samples |
| LM285DRE4-2-5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 285-25 | Samples |
| LM285DRG4-2-5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 285-25 | Samples |
| LM285LP-2-5 | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | -40 to 85 | 285-25 | Samples |
| LM285LPE[redacted] | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | -40 to 85 | 285-25 | Samples |
| LM285LPR-2-5 | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | -40 to 85 | 285-25 | Samples |
| LM285LPRE3-2-5 | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | -40 to 85 | 285-25 | Samples |
| LM385BD-2-5 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 385B25 | Samples |
| LM385BDE4-2-5 | | | | | | | | | | | |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| LM385BLPE3-2-5 | ACTIVE | | | | | | | | | | |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) |
|---|---|---|---|---|---|---|---|---|---|---|




4040047-3/M 06/11

B. This drawing is subject to change with

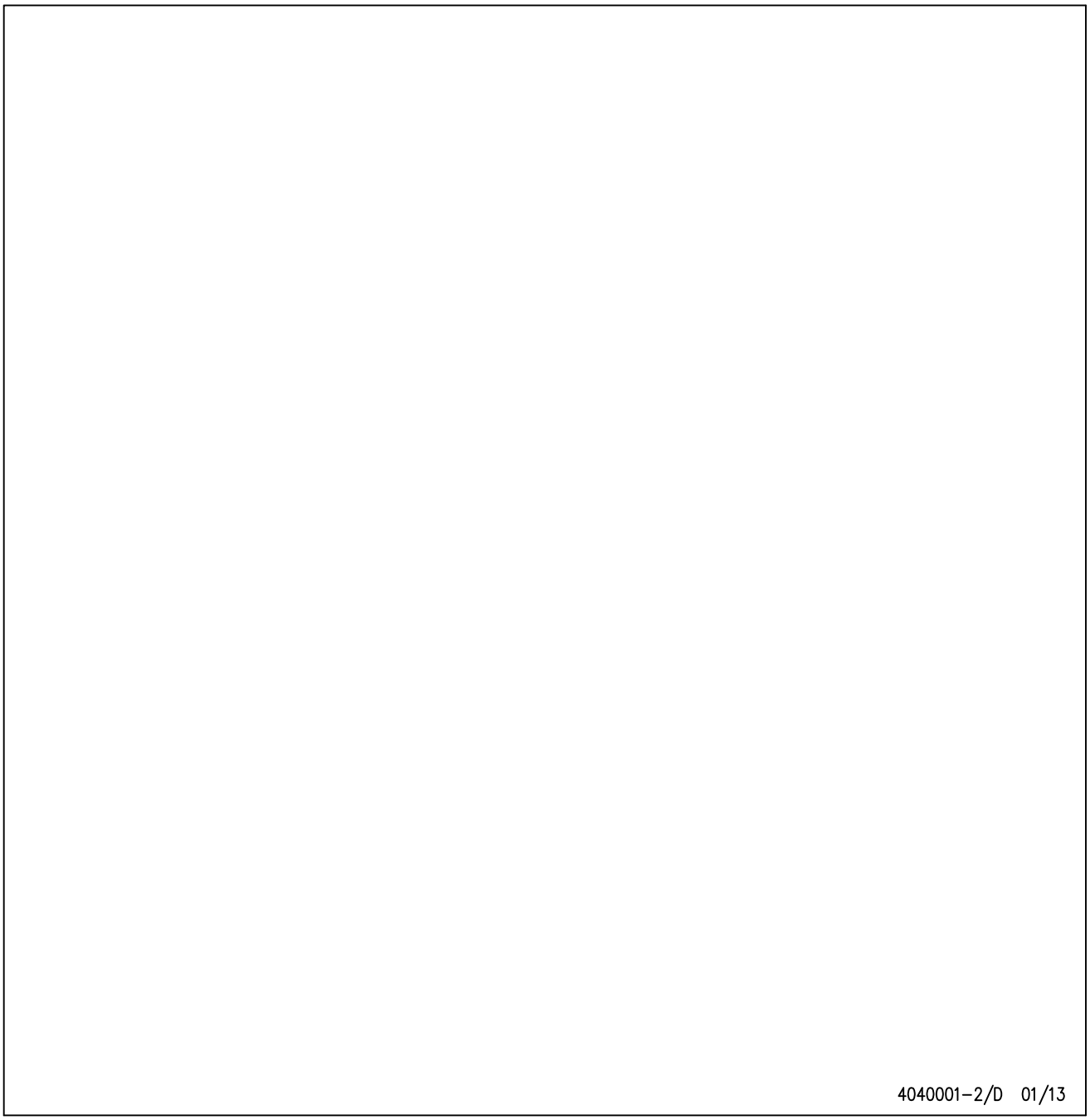
Example
Pad Geometry
(See Note C)

Example
Solder Mask Opening
(See Note E)

C. Publication IPC–7351 is recommended for alternate designs.

D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.

E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.




NOTES: A. All linear dimensions are in inches (millimeters).

C Lead dimensions are not controlled within this area.

D Falls within JEDEC TO–226 Variation AA (TO–226 replaces TO–

9 (13,70)

0.020 (0,5

0.384 (9,75)
0.335 (8,50)

TAPE & REEL

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